

In the claims:

Please amend the claims as follows:

30. (Currently Amended) A defective semiconductor package comprising:
- (a) a defective substrate having a first surface with a pattern of conductors;
 - (b) the defective substrate having a second surface including a defective die attach site;
 - (c) a wire bond slot forming an opening through the defective substrate extending from the first surface to the second surface; and
 - (d) a cover member attached to the defective substrate on the second surface so as to cover at least a portion of the opening, wherein the cover member does not comprise a functional die.
31. (Original) The defective semiconductor package of claim 30, wherein the cover member comprises tape.
32. (Original) The defective semiconductor package of claim 30, wherein the cover member covers a majority of the opening.
36. (Previously added) The defective semiconductor package of claim 30, wherein the cover member covers from about 70% to about 98% of the opening formed by the wire bond slot.
37. (Previously added) The defective semiconductor package of claim 30, wherein the wire bond slot is associated with the defective die attach site.
38. (Previously added) The defective semiconductor package of claim 30, wherein the cover member comprises a defective die.
39. (Previously added) The defective semiconductor package of claim 30, wherein the cover member covers from about 80% to about 90% of the opening formed by the wire bond slot.

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40. (Previously added) The defective semiconductor package of claim 30, wherein the cover member covers at least about 70% of the opening formed by the wire bond slot.